Materials Declaration

Package	LQFP
Body Size	12 X 12 X 1.4
LeadCount	80
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica Fused	87.5	3.58 E-01	721354
Phenol Resin	5.5	2.25 E-02	45342
Epoxy Resin	3.0	1.23 E-02	24732
Epoxu, Cresol Novolac	3.0	1.23 E-02	24732
Brominated Epoxy Resin	0.6	2.25 E-03	4534
Antimony Trioxide	0.5	2.05 E-03	4122
Carbon Black	0.3	1.23 E-03	2473

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.3	6.98 E-02	140526
Sn	0.3	1.76 E-04	354
Zn	0.3	1.76 E-04	354
Cr	0.2	1.55 E-04	312

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	6.23 E-05	125

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	2.72 E-03	5483

Bond Wires

	% of Wire	Weight (g)	PPM
Au	100.0	5.20 E-03	10467

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	6.68 E-03	13458

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Silver flake	77.5	5.76 E-04	1159
Diglycidylether bisphenol-F	12.5	9.28 E-05	187
Epoxy resin	8.0	5.94 E-05	120
gamma Butyrolactone	8.0	5.94 E-05	120
Mixed aryl allyl glycidyl compounds	3.0	2.23 E-05	45

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA Method #3052
Cd	Not Detected	US EPA Method #3052
Hg	Not Detected	US EPA Method #3052
Cr+6	Not Detected	US EPA Method #7196A and #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Die Attach Paste

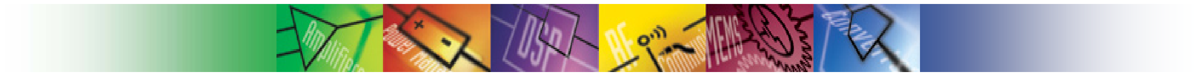
Item	PPM	Method
Pb	27.50	US EPA Method #3050B
Cd	Not Detected	EN1122: Method 2001 B
Hg	Not Detected	US EPA Method #3052
Cr+6	Not Detected	US EPA Method #7196A and #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Package Totals

Weight (g)	PPM
4.97 E-01	1000000

AST-ST-B

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



Materials Declaration

Package	LQFP
Body Size	12 X 12 X 1.4
LeadCount	80
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica Fused	87.5	3.58 E-01	721354
Phenol Resin	5.5	2.25 E-02	45342
Epoxy Resin	3.0	1.23 E-02	24732
Epoxu, Cresol Novolac	3.0	1.23 E-02	24732
Brominated Epoxy Resin	0.6	2.25 E-03	4534
Antimony Trioxide	0.5	2.05 E-03	4122
Carbon Black	0.3	1.23 E-03	2473

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.3	6.98 E-02	140526
Sn	0.3	1.76 E-04	354
Zn	0.3	1.76 E-04	354
Cr	0.2	1.55 E-04	312

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	6.23 E-05	125

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.0	2.31 E-03	4661
Pb	15.0	4.08 E-04	823

Bond Wires

	% of Wire	Weight (g)	PPM
Au	100.0	5.20 E-03	10467

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	6.68 E-03	13458

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Silver flake	77.5	5.76 E-04	1159
Diglycidylether bisphenol-F	12.5	9.28 E-05	187
Epoxy resin	8.0	5.94 E-05	120
gamma Butyrolactone	8.0	5.94 E-05	120
Mixed aryl allyl glycidyl compounds	3.0	2.23 E-05	45

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA Method #3052
Cd	Not Detected	US EPA Method #3052
Hg	Not Detected	US EPA Method #3052
Cr+6	Not Detected	US EPA Method #7196A and #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	27.50	US EPA Method #3050B
Cd	Not Detected	EN1122: Method 2001 B
Hg	Not Detected	US EPA Method #3052
Cr+6	Not Detected	US EPA Method #7196A and #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Package Totals

Weight (g)	PPM
4.97 E-01	1000000

AST-ST-A

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